



NEW APPLICATION TRANSMITTAL - UTILITY

Transmitted herewith for filing is the patent application of Jackson HSIEH and Jichen WU for "SUBSTRATE STRUCTURE FOR AN INTEGRATED CIRCUIT PACKAGE AND METHOD FOR MANUFACTURING THE SAME".

1. Type Of Application

This application is an original utility application.

2. Benefit Of Prior Application

Applicant claims no benefit of prior application.

3. Fee Calculation

CLAIMS AS FILED			
			Basic Fee = \$375.00
Total:	6 - 20 =	0 x \$ 9.00 =	0.00
Ind.:	2 - 3 =	0 x \$42.00 =	0.00
Multiple dependent:		0 x \$140.00 =	<u>0.00</u>

Basic Filing Fee Calculation = \$375.00

4. Small Entity Statement

Applicant is entitled to Small Entity Status.

5. Fee Payment Being Made At This Time

Required Fees:

<u>x</u> Basic Filing Fee	<u>\$375.00</u>
Total Fees	\$375.00

Please charge the above and any deficiencies in fees to Deposit Acct # 16-2497.

6. Papers Enclosed Which Are Required For Filing Date Under 37 CFR 1.53(b)

6 Pages of specification

2 Pages of claims

1 Page of abstract

2 Sheets of formal drawings

7. Declaration or Oath

A Combined Declaration and Power of Attorney executed by each inventor is enclosed herewith.

8. Certificate of Mailing (37 CFR 1.10): I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as Express Mail in an envelope addressed to: Mail Stop New Applications, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Respectfully submitted,

Date: July 16, 2003

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